NSS1C201MZ4, **NSV1C201MZ4**

100 V, 2.0 A, Low V_{CE(sat)} **NPN Transistor**

ON Semiconductor's e²PowerEdge family of low V_{CE(sat)} transistors are miniature surface mount devices featuring ultra low saturation voltage (V_{CE(sat)}) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	100	Vdc
Collector-Base Voltage	V _{CBO}	140	Vdc
Emitter-Base Voltage	V _{EBO}	7.0	Vdc
Collector Current - Continuous	I _C	2.0	Α
Collector Current - Peak	I _{CM}	3.0	Α

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	155	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 2)	2.0 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	64	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P _{Dsingle} (Note 3)	710	mW
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

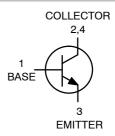
- 1. FR-4 @ 7.6 mm², 1 oz. copper traces.
- 2. FR-4 @ 645 mm², 1 oz. copper traces.
- 3. Thermal response.



ON Semiconductor®

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100 VOLTS, 2.0 AMPS NPN LOW V_{CE(sat)} TRANSISTOR



MARKING DIAGRAM



SOT-223 **CASE 318E** STYLE 1



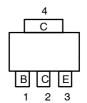
= Assembly Location

= Year

= Work Week

= Specific Device Code = Pb-Free Package

PIN ASSIGNMENT



Top View Pinout

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS1C201MZ4T1G NSV1C201MZ4T1G	SOT-223 (Pb-Free)	1000/ Tape & Reel
NSS1C201MZ4T3G	SOT-223 (Pb-Free)	4000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NSS1C201MZ4, NSV1C201MZ4

$\textbf{ELECTRICAL CHARACTERISTICS} \ (T_A = 25^{\circ}C \ unless \ otherwise \ noted)$

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I _C = 10 mAdc, I _B = 0)	V _{(BR)CEO}	100			Vdc
Collector – Base Breakdown Voltage (I _C = 0.1 mAdc, I _E = 0)	V _{(BR)CBO}	140			Vdc
Emitter – Base Breakdown Voltage (I _E = 0.1 mAdc, I _C = 0)	V _{(BR)EBO}	7.0			Vdc
Collector Cutoff Current (V _{CB} = 140 Vdc, I _E = 0)	I _{CBO}			100	nA
Emitter Cutoff Current (V _{EB} = 6.0 Vdc)	I _{EBO}			50	nA
ON CHARACTERISTICS					
DC Current Gain (Note 4) $ (I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V}) $ $ (I_C = 500 \text{ mA}, V_{CE} = 2.0 \text{ V}) $ $ (I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}) $ $ (I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}) $	h _{FE}	150 120 80 40		360	
Collector – Emitter Saturation Voltage (Note 4) $ (I_C = 0.1 \text{ A}, I_B = 0.010 \text{ A}) $ $ (I_C = 0.5 \text{ A}, I_B = 0.050 \text{ A}) $ $ (I_C = 1.0 \text{ A}, I_B = 0.100 \text{ A}) $ $ (I_C = 2.0 \text{ A}, I_B = 0.200 \text{ A}) $	V _{CE(sat)}			0.030 0.060 0.100 0.180	V
Base – Emitter Saturation Voltage (Note 4) (I _C = 1.0 A, I _B = 0.100 A)	V _{BE(sat)}			1.10	V
Base – Emitter Turn–on Voltage (Note 4) (I _C = 1.0 A, V _{CE} = 2.0 V)	V _{BE(on)}			0.850	V
Cutoff Frequency (I_C = 100 mA, V_{CE} = 5.0 V, f = 100 MHz)	f _T		100		MHz
Input Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	Cibo		305		pF
Output Capacitance (V _{CB} = 3.0 V, f = 1.0 MHz)	Cobo		22		pF

^{4.} Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

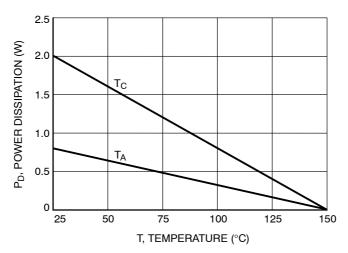
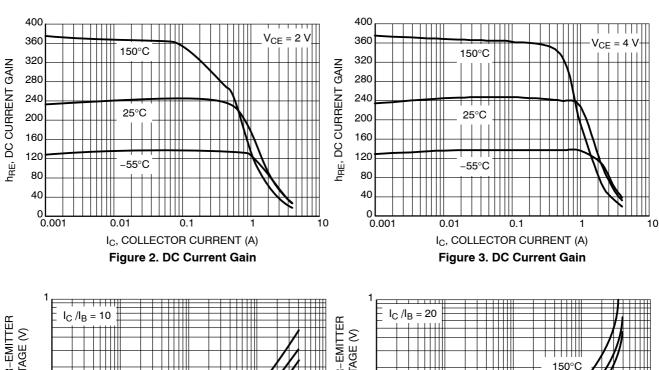


Figure 1. Power Derating

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TYPICAL CHARACTERISTICS



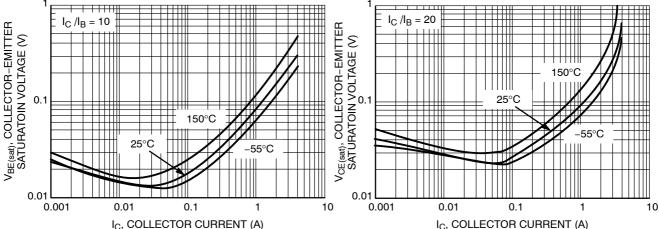


Figure 4. Collector-Emitter Saturation Voltage

Figure 5. Collector-Emitter Saturation Voltage

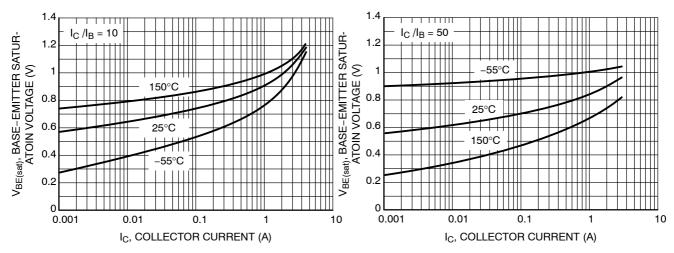
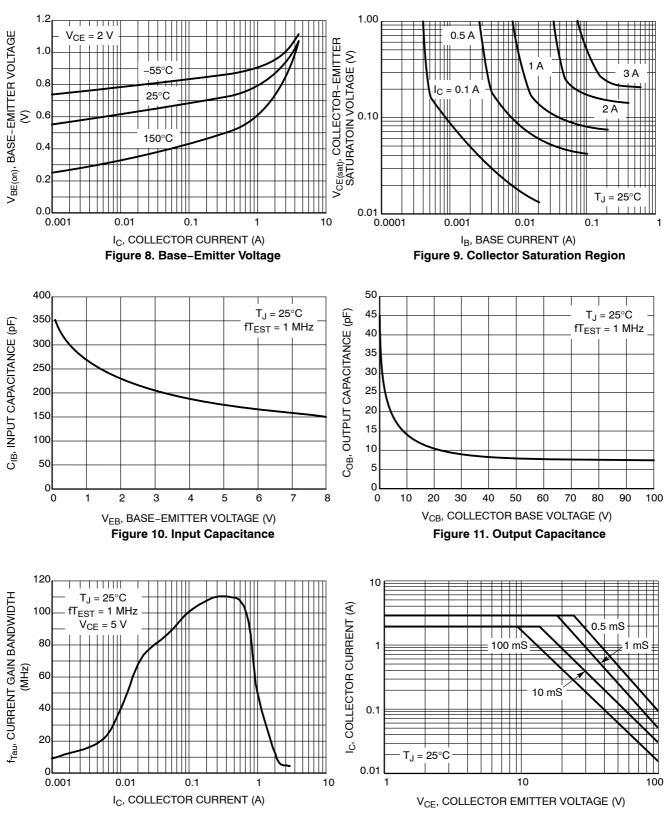


Figure 6. Base-Emitter Saturation Voltage

Figure 7. Base-Emitter Saturation Voltage

NSS1C201MZ4, NSV1C201MZ4

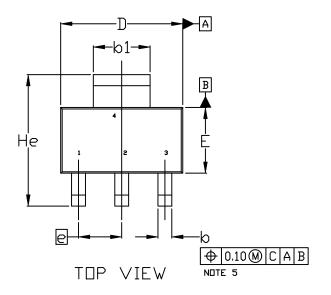
TYPICAL CHARACTERISTICS

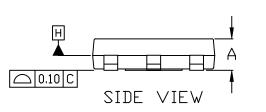


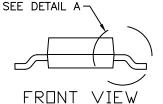


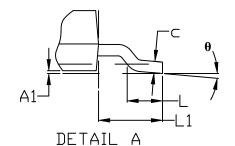
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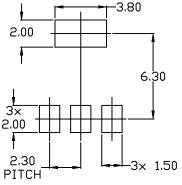




NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
 MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. ALLIS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
Ø	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
U	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
е	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0°		10°	



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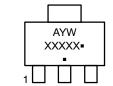
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DATE 02 OCT 2018

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	STYLE 9: PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	STYLE 12: PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

GENERIC MARKING DIAGRAM*



A = Assembly Location

Y = Year W = Work Week

not follow the Generic Marking.

XXXXX = Specific Device Code

= Pb-Free Package

(Note: Microdot may be in either location)
*This information is generic. Please refer to
device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "•", may
or may not be present. Some products may

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